IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Carial No.	10/330,881
Priority Application Serial No.	
	December 23, 2002 Trung Tri Doan et al. Micron Technology, Inc.
Inventor	Micron Technology, Inc.
Assignee	2813
Priority Group Art Unit	David S. Blum
Priority Examiner	MI22-2416
Customer No	Methods of Forming Trench Isolation Regions
Title	Methods of Forming French fortunes.

INFORMATION DISCLOSURE STATEMENT PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending application Serial No. 10/330,881, filed December 23, 2002. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 10-16-03

By: Mark S. Matkin
Reg. No. 32,268

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO. MI22-2416

PRIORITY SERIAL NO. 10/330,881

LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)

APPLICANT: Trung Tri Doan et al.

PRIORITY FILING DATE

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Examiner's		Document Number		Date	Name		Class	Subclass	Filing If Appro	Date opriate	
Initials		3,990,927		11/1976	Montier						
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	A.	02277253	Α	11/1990	Japan (Hayashide et al	.)					
	AK	146224		01/1996	Japan						
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considered. Include copy of this form with next communication to applicant.

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